

ABSTRACT

Provided is a method for manufacturing electronic component improved in chip-holding efficiency, pickup efficiency and contamination resistance in a well-balanced manner, the method comprising a semi-cured adhesive layer-forming step of forming a semi-cured adhesive layer on the rear face of a wafer, a fixing step of fixing the semi-cured adhesive layer of the wafer on a ring frame with a cohesive sheet, a dicing step of dicing the wafer into semiconductor chips, a UV-irradiating step of irradiating ultraviolet ray, and a pick-up step of picking up the chips and semi-cured adhesive layers from the cohesive layer, wherein the cohesive sheet has a cohesive layer of a cohesive agent having a particular composition formed on one face of its base film.